











LM337L

SNVS780E -MAY 1998-REVISED DECEMBER 2016

LM337L 3-Terminal Adjustable Regulator

Features

- Adjustable Output Down to 1.2 V
- Ensured 100-mA Output Current
- Line Regulation Typically 0.01%/V
- Load Regulation Typically 0.1%
- **Current Limit Constant With Temperature**
- Eliminates the Need to Stock Many Voltages
- Standard 3-Pin Transistor Package
- 80-dB Ripple Rejection
- Output is Short Circuit Protected

Applications

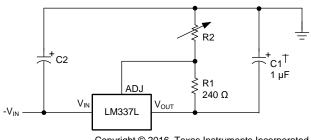
- **Industrial Power Supplies**
- **Factory Automation Systems**
- **Building Automation Systems**
- **PLC Systems**
- Instrumentation
- **IGBT** Drive Negative Gate Supplies
- Networking
- Set-Top Boxes

3 Description

The LM337L is an adjustable 3-pin negative voltage regulator capable of supplying 100 mA over a -1.2-V to -37-V output range. The LM337L is easy to use and requires only two external resistors to set the output voltage. Both line and load regulation are better than standard fixed regulators. The LM337L is packaged in a standard, easy-to-use TO-92 transistor package.

In addition to higher performance than fixed regulators, the LM337L offers full overload protection. Included on the chip are current limit, thermal overload protection, and safe area protection. All overload protection circuitry remains fully functional even if the adjustment pin is disconnected.

1.2-V to 25-V Adjustable Regulator



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Normally, only a single 1-µF solid tantalum output capacitor is required unless the device is situated more than 6 inches from the input filter capacitors, in which case an input bypass is required. A larger output capacitor can be added to improve transient response. The adjustment pin can be bypassed to achieve very high ripple rejection ratios, which are difficult to achieve with standard 3-pin regulators.

Besides replacing fixed regulators, the LM337L is useful in a wide variety of other applications. Because the regulator is floating and monitors only the inputto-output differential voltage, supplies of several hundred volts can be regulated as long as the maximum input-to-output differential is not exceeded.

The LM337L makes a simple adjustable switching regulator, a programmable output regulator, or by connecting a fixed resistor between the adjustment and output, the LM337L can be used as a precision current regulator. Supplies with electronic shutdown can be achieved by clamping the adjustment pin to ground, which programs the output to 1.2 V, where most loads draw little current.

The LM337L is available in a standard TO-92 transistor package and a standard SO-8 surface mount package. The LM337L is rated for operation over a -25°C to 125°C range.

For applications requiring output current in excess of 0.5 A and 1.5 A, The LM137 series may be suitable. For the positive complement, the LM117 and LM317L series are options.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)		
I M2271	SOIC (8)	3.91 mm × 4.90 mm		
LM337L	TO-92 (3)	4.30 mm × 4.30 mm		

(1) For all available packages, see the orderable addendum at the end of the data sheet.

LM337L Available Packages

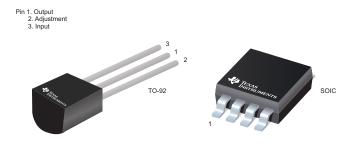




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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (May 2013) to Revision E

Page

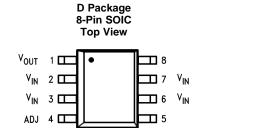
•	Added Applications section, Device Information table, Pin Configuration and Functions section, ESD Ratings table,	
	Recommended Operating Conditions table, Typical Characteristics section, Detailed Description section, Application	
	and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation	
	Support section, and Mechanical, Packaging, and Orderable Information section	. 1
•	Deleted DSBGA Package references throughout the data sheet	1
•	Deleted soldering information rows from Absolute Maximum Ratings table	3
•	Added Thermal Information table	4
•	Changed R _{0JA} values for D (SOIC) package From: 180 To: 111.3 and for LP (TO-92) package From: 160 To: 156.9	. 4

Changes from Revision C (May 2013) to Revision D

Page



5 Pin Configuration and Functions







Pin Functions

	PIN		I/O	DESCRIPTION
NAME	TO-92	SOIC	1/0	DESCRIPTION
ADJ	1	4	_	Adjust pin
NC	_	5, 8	_	No connection
VIN	3	2, 3, 6, 7	Input	Input voltage pin for the regulator
VOUT	2	1	Output	Output voltage pin for the regulator

6 Specifications

6.1 Absolute Maximum Ratings

See (1)(2)

	MIN	MAX	UNIT
Input-output voltage differential		40	٧
Power dissipation	Internall	y Limited	
Storage temperature, T _{stg}	-55	150	ô

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)(2)	±1500	٧

JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Pins listed as ±1500 V may actually have higher performance.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Operating junction temperature	-25	125	°C

Product Folder Links: LM337L

⁽²⁾ If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

⁽²⁾ Human-body model, 1.5k Ω in series with 100 pF.



6.4 Thermal Information

		LM		
	THERMAL METRIC ⁽¹⁾	D (SOIC)	LP (TO-92)	UNIT
		8 PINS	3 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	111.3	156.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	56.1	80.2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	51.9	_	°C/W
ΨЈТ	Junction-to-top characterization parameter	10.6	24.7	°C/W
ΨЈВ	Junction-to-board characterization parameter	51.3	136.2	°C/W

⁽¹⁾ For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Electrical Characteristics(1)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Line regulation ⁽²⁾	$T_A = 25^{\circ}C, 3 \text{ V} \le V_{IN} - V_{OUT} \le 40 \text{ V}$		0.01	0.04	%/V
Load regulation (2)	$T_A = 25^{\circ}C$, 5 mA $\leq I_{OUT} \leq I_{MAX}$		0.1%	0.5%	
Thermal regulation	T _A = 25°C, 10-ms Pulse		0.04	0.2	%/W
Adjustment pin current			50	100	μА
Adjustment pin current change	$5 \text{ mA} \le I_L \le 100 \text{ mA}, 3 \text{ V} \le V_{IN} - V_{OUT} \le 40 \text{ V}$		0.2	5	μА
Reference voltage	$3 \text{ V} \le V_{\text{IN}} - V_{\text{OUT}} \le 40 \text{ V}, 10 \text{ mA} \le I_{\text{OUT}} \le 100 \text{ mA}, P \le 625 \text{ mW}$	1.2	1.25	1.3	V
Line regulation ⁽²⁾	$3 \text{ V} \le V_{\text{IN}} - V_{\text{OUT}} \le 40 \text{ V}$		0.02	0.07	%/V
Load regulation (2)	5 mA ≤ I _{OUT} ≤ 100 mA		0.3%	1.5%	
Temperature stability	$T_{MIN} \le T_j \le T_{MAX}$		0.65%		
Minimum load current	$ V_{IN} - V_{OUT} \le 40 \text{ V}$		3.5	5	mA
Minimum load current	$3 \text{ V} \le V_{\text{IN}} - V_{\text{OUT}} \le 15 \text{ V}$		2.2	3.5	mA
Commont limit	$3 \text{ V} \le V_{\text{IN}} - V_{\text{OUT}} \le 13 \text{ V}$	100	200	320	mA
Current limit	$ V_{IN} - V_{OUT} = 40 \text{ V}$	25	50	120	mA
RMS output noise, % of V _{OUT}	T _A = 25°C, 10 Hz ≤ f ≤ 10 kHz		0.003%		
Chermal regulation Adjustment pin current Adjustment pin current change Reference voltage Line regulation (2) Load regulation (2) Cemperature stability Minimum load current Current limit RMS output noise, % of V _{OUT}	$V_{OUT} = -10 \text{ V}, F = 120 \text{ Hz}, C_{ADJ} = 0$		65		dB
Rippie rejection ratio	$C_{ADJ} = 10 \mu F$	66	80		dB
Long-term stability	T _A = 125°C		0.3%	1%	

⁽¹⁾ Unless otherwise specified, these specifications apply $-25^{\circ}\text{C} \le T_{J} \le 125^{\circ}\text{C}$ for the LM337L; $|V_{IN} - V_{OUT}| = 5 \text{ V}$ and $I_{OUT} = 40 \text{ mA}$. Although power dissipation is internally limited, these specifications are applicable for power dissipations up to 625 mW. I_{MAX} is 100 mA.

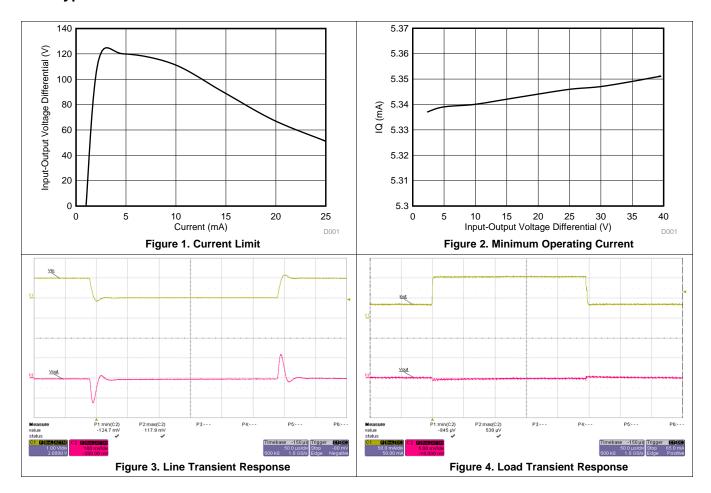
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⁽²⁾ Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specification for thermal regulation.



6.6 Typical Characteristics



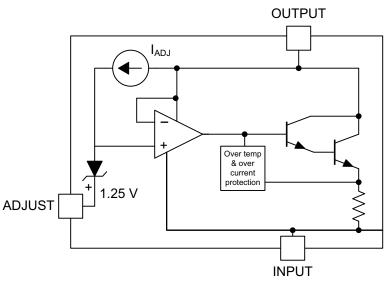


7 Detailed Description

7.1 Overview

The LM337L devices are adjustable 3-terminal negative-voltage regulators capable of supplying 100 mA over an output voltage range of –1.2 V to –37 V. They are exceptionally easy to use, requiring only two external resistors to set the output voltage and one output capacitor for frequency compensation. In addition, LM337L offers full overload protection. Included on the chip are current limit, thermal overload protection and safe area protection. All overload protection circuitry remains fully functional even if the adjustment terminal is disconnected. The LMx37 devices serve a wide variety of applications, including local on-card regulation, programmable output-voltage regulation, and precision current regulation.

7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Output Voltage Adjustment

The Adjustment (ADJ) pin serves as a voltage adjustment reference for the output. The ADJ pin can be attached to a resistor divider circuit to adjust the output voltage level. The reference voltage VADJ will typically be 1.25 V higher than VO.

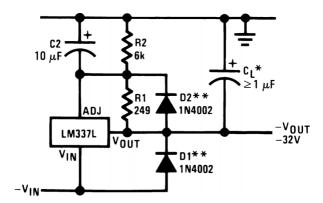
7.4 Device Functional Modes

7.4.1 Protection Diodes

When external capacitors are used with any IC regulator, it is sometimes necessary to add protection diodes to prevent the capacitors from discharging through low current points into the regulator. Most 10-µF capacitors have low enough internal series resistance to deliver 20-A spikes when shorted. Although the surge is short, there is enough energy to damage parts of the IC. When an output capacitor is connected to a negative output regulator and the input is shorted, the output capacitor pulls current out of the output of the regulator. The current depends on the value of the capacitor, the output voltage of the regulator, and the rate at which VIN is shorted to ground. The bypass capacitor on the adjustment terminal can discharge through a low current junction. Discharge occurs when either the input, or the output, is shorted. Figure 15 shows the placement of the protection diodes.



Device Functional Modes (continued)



When CL is larger than 20 μ F, D1 protects the LM337L in case the input supply is shorted. When C2 is larger than 10 μ F and \neg VOUT is larger than \neg 25V, D2 protects the LM337L in case the output is shorted.

Figure 5. Regulator With Protection Diodes



8 Application and Implementation

NOTE

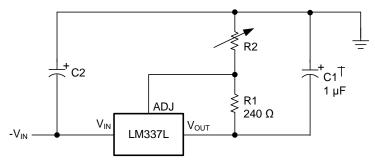
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LM337L is a negative output linear regulator with high accuracy and a wide temperature range. An output capacitor can be added to further improve transient response, and the ADJ pin can be bypassed to achieve very high ripple-rejection ratios. The device's functionality can be utilized in many different applications that require negative voltage supplies, such as bipolar amplifiers, operational amplifiers, and constant current regulators.

8.2 Typical Applications

8.2.1 1.2-V to 25-V Adjustable Regulator



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Full output current not available at high input-output voltages

 $\dagger C1 = 1-\mu F$ solid tantalum or $10-\mu F$ aluminum electrolytic required for stability

*C2 = 1-µF solid tantalum is required only if regulator is more than 4" from power supply filter capacitor

Figure 6. 1.2-V to 25-V Adjustable Regulator Diagram

8.2.1.1 Design Requirements

The device component count is very minimal, employing two resistors as part of a voltage divider circuit and an output capacitor for load regulation. An input capacitor is needed if the device is more than 4 in. from the filter capacitors.

8.2.1.2 Detailed Design Procedure

The output voltage is set based on the selection of the two resistors (R1 and R2) as shown in Equation 1.

$$-V_{OUT} = -1.25 V \left(1 + \frac{R2}{240 \Omega} \right)$$
 (1)



Typical Applications (continued)

8.2.1.3 Application Curve

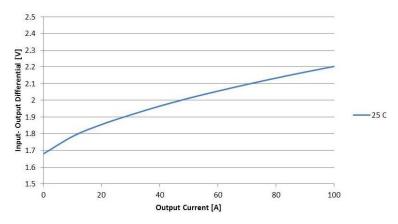
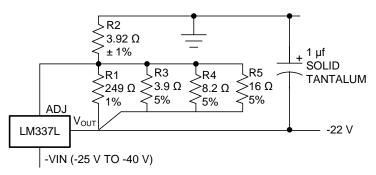


Figure 7. Dropout Voltage across Load Current at 25°C (△Vout < 100 mV

8.2.2 Regulator With Trimmable Output Voltage



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Figure 8. Regulator with Trimmable Output Voltage Diagram

8.2.2.1 Design Requirements

This design uses five resistors with two being used for a voltage divider circuit and the other three used for trimming the output voltage. The benefit is lower cost as compared to using a trim pot. An output capacitor is needed to improve load regulation.

8.2.2.2 Detailed Design Procedure

This design will trim the output voltage to within 1% of -22 V. The parallel combination of R1, R3, R4 and R5 serve as the bottom resistance and R2 as the top resistance in the voltage divider that sets the output voltage.

Trim Procedure:

- If V_{OUT} is –23.08 V or larger, do not use R3, otherwise leave it in.
- Then if V_{OUT} is -22.47 V or bigger, do not use R4, otherwise leave it in.
- Then if V_{OUT} is -22.16 V or bigger, do not use R5, otherwise leave it in.

This will trim the output to well within 1% of -22 V_{DC}, without any of the expense or trouble of a trim pot (see LB-46). This technique can be used at any output voltage level.

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9 Power Supply Recommendations

The input supply to the LM337L must be kept at a voltage level such that its maximum input to output differential voltage rating is not exceeded. The minimum dropout voltage must also be met with extra headroom when possible to keep the LM337L in regulation. TI recommends an input capacitor, especially when the input pin is placed more than 4 in. away from the power-supply filter capacitor.

10 Layout

10.1 Layout Guidelines

Some layout guidelines must be followed to ensure proper regulation of the output voltage with minimum noise. Traces carrying the load current must be wide to reduce the amount of parasitic trace inductance and the feedback loop from VOUT to ADJ must be kept as short as possible. To improve PSRR, a bypass capacitor can be placed at the ADJ pin and must be placed as close as possible to the IC. In cases when VIN shorts to ground, an external diode must be placed from VIN to VOUT to divert the surge current into the output capacitor and protect the IC. Similarly, in cases when a large bypass capacitor is placed at the ADJ pin and VOUT shorts to ground, an external diode must be placed from VOUT to ADJ to provide a path for the bypass capacitor to discharge. These diodes must be placed close to the corresponding IC pins to increase their effectiveness.

10.2 Layout Example

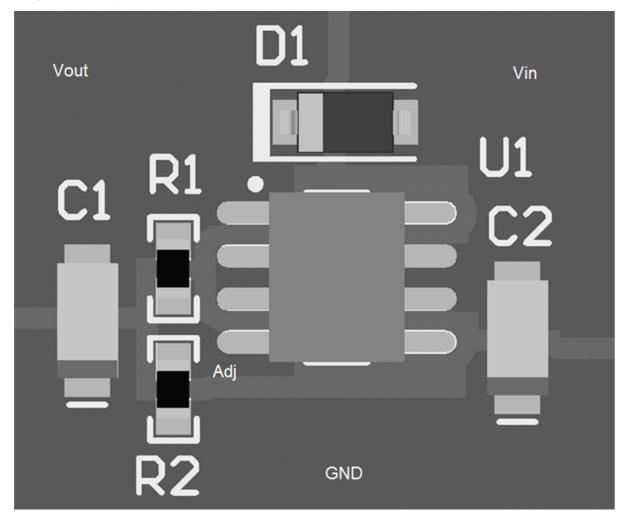


Figure 9. LM337L Layout Example



11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

For related documentation see the following:

- LM317L-N 3-Terminal Adjustable Regulator (SNOSBW2)
- LM117, LM317-N Wide Temperature Three-Pin Adjustable Regulator (SNVS774)
- LM317L-N 3-Terminal Adjustable Regulator (SNVS775)

11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Lise

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 Trademarks

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11.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.6 Glossary

SLYZ022 — TI Glossarv.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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8-Oct-2015

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM337LM	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-25 to 100	LM337 LM	
LM337LM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 100	LM337 LM	Samples
LM337LMX	NRND	SOIC	D	8	2500	TBD	Call TI	Call TI	-25 to 100	LM337 LM	
LM337LMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 100	LM337 LM	Samples
LM337LZ/LFT3	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type		LM337 LZ	Samples
LM337LZ/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	CU SN	N / A for Pkg Type	-25 to 100	LM337 LZ	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

8-Oct-2015

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

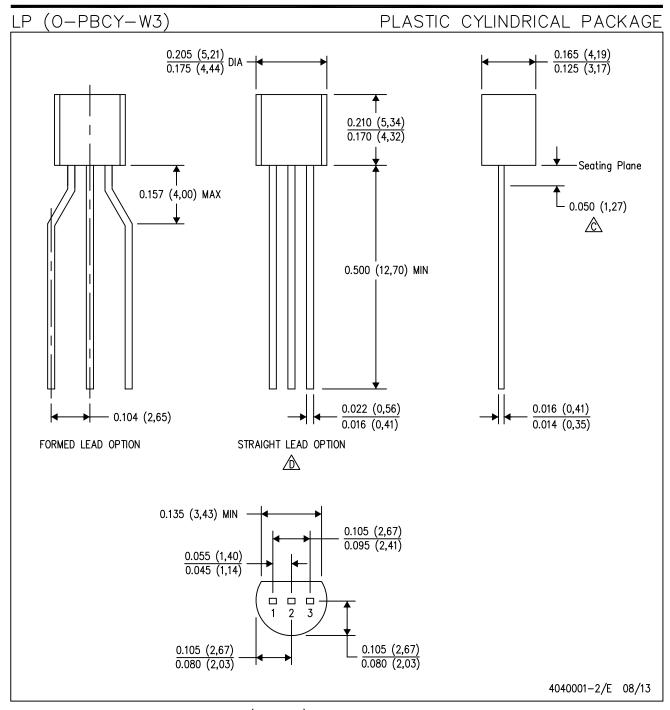
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM337LMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM337LMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM337LMX	SOIC	D	8	2500	367.0	367.0	35.0
LM337LMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Lead dimensions are not controlled within this area.

Falls within JEDEC TO−226 Variation AA (TO−226 replaces TO−92).

E. Shipping Method:

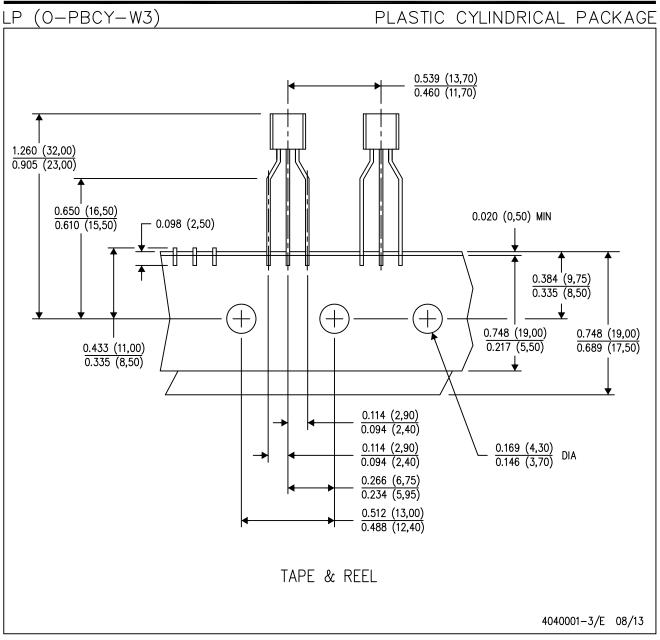
Straight lead option available in bulk pack only.

Formed lead option available in tape & reel or ammo pack.

Specific products can be offered in limited combinations of shipping mediums and lead options.

Consult product folder for more information on available options.





NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Tape and Reel information for the Formed Lead Option package.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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